PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
FEI ZHOU	04/27/2018

RECEIVING PARTY DATA

Name:	SEMICONDUCTOR MANUFACTURING INTERNATIONAL (SHANGHAI) CORPORATION
Street Address:	18 ZHANGJIANG ROAD, PUDONG NEW AREA
City:	SHANGHAI
State/Country:	CHINA
Postal Code:	201203
Name:	SEMICONDUCTOR MANUFACTURING INTERNATIONAL (BEIJING) CORPORATION
Street Address:	NO. 18, WEN CHANG RD., ECONOMIC-TECHNOLOGICAL DEVELOPMENT AREA, DAXING DISTRICT
City:	BEIJING
State/Country:	CHINA
Postal Code:	100716

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15971002

CORRESPONDENCE DATA

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NAME OF SUBMITTER:	LUCILLA FAN
SIGNATURE:	/Lucilla Fan/

DATE SIGNED:	05/04/2018
Total Attachments: 2 source=DeclAssig00158052200#page1.tif source=DeclAssig00158052200#page2.tif	

ASSIGNMENT AND DECLARATION

WHEREAS I/We, the below named inventor(s) (hereinafter referred to as Assignor(s)) have made an invention entitled:

SEMICONDUCTOR DEVICES AND FABRICATION METHODS THEREOF

for which I/We executed an application for United States Letters Patent concurrently herewith or filed an application for United States Letters Patent on _________ (Application No. _____________); and

WHEREAS, Semiconductor Manufacturing International (Shanghai) Corporation, a corporation of P. R. China whose post office address is 18 Zhangjiang Road, Pudong New Area, Shanghai, China 201203, and Semiconductor Manufacturing International (Beijing) Corporation, a corporation of P. R. China whose post office address is No. 18, Wen Chang Rd., Economic-Technological Development Area, Daxing District, Beijing, China 100716 (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from Assignee is hereby acknowledged, I/We, as Assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the Assignee, its lawful successors and assigns, my/our entire right, title, and interest in and to this invention, provisional Application No. ________, filed ____________ (if any), and this application, and all divisions, substitutions, continuations, and continuations-in-part thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof, and all rights to claim priority on the basis of the above provisional application (if any), as well as all rights to claim priority on the basis of this application, and all applications for Letters Patent which may hereafter be filed for this invention in any foreign country and all Letters Patent which may be granted on this invention in any foreign country, and all extensions, renewals, and reissues thereof; and I/We hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any foreign country whose duty it is to issue patents on applications as described above, to issue all Letters Patent for this invention to Assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY covenant that I/We have the full right to convey the interest assigned by this Assignment, and I/We have not executed and will not execute any agreement in conflict with this Assignment;

AND, I/WE HEREBY further covenant and agree that I/We will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to me/us respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/we have empowered in the Declaration and Power of Attorney in this application, to insert here in parentheses (Application No. _______, filed ___________________) the filing date and application number of said application when known.

Further, as a below named inventor, I hereby declare that:

This declaration is directed to the application attached hereto or United States application or PCT international application number ____________________ filed on ____________________. If the application is not attached hereto, the application is as identified above or by the attorney docket number as set forth above and/or the following.

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I have reviewed and understand the contents of the above-identified application, including the claims.

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37,Code of Federal Regulations § 1.56, including for continuation-in-part applications, material information which became available between the filing data of the prior application and the national or PCT International filing date of the continuation-in-part application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. §1001 by fine or imprisonment of not more than five (5) years, or both.

IN TESTIMONY WHEREOF, I/We have hereunto set our hands.

Inventor 1 Legal Name: Fei ZHOU

Signature: Fei Zhou Date: 2018.4.27

Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form or must have been previously filed. Check the box below and complete the attached page(s) to list additional inventors.

☐ Additional inventors are being named on the ___ supplemental sheet(s) attached hereto.